

BIB & HAST BOARDS

HTOL and HAST testing



Key Features

HTOL

- BIB for elevated temperatures
- Boards for all Burn-in systems
- Extensive design library
- Designs using all socket types
- Fine pitch layouts

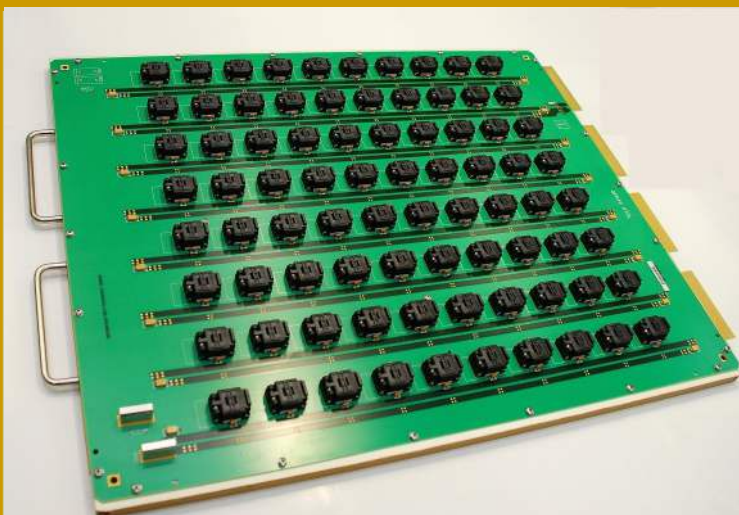
HAST

- Boards for HAST and THB
- Designs for all package types
- Silicone conformal coating
- Lead free assemblies
- Boards for all chamber types

Add-ons

- Bibtest55 XL BIB test system
- Socket test probes
- Stainless steel chamber racks
- Full turn-key system solutions

BIB for all system types



Product Highlights

□ Overview

Abrel Products have been a market leader in the design and manufacture of burn-in boards since 1994, and are an approved global supplier to all of the major semiconductor companies. Boards can be supplied for all system types, with solutions available for many test conditions, including HTOL, PTC, HAST and 85/85.

□ Fine Pitch

Abrel manufactures boards for all the latest technologies, including fine pitch to 0.35mm and WLCSP wafer level. Abrel have an experienced engineering team with a design capability which includes layouts featuring technologies such as buried, blind, filled and capped vias, complete with laser drilling.

□ Product Overview

- High temp BIB applications to 300°C.
- HAST boards with long operating life.
- Board designs for all package types.
- Over 5000 designs completed to date.
- Large inventory of BI sockets in stock.
- Fast delivery times.
- ISO9001:2008 certified.

Summary Product Specifications

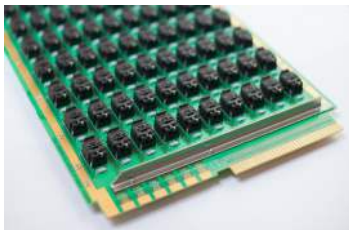
Board Design

CAD systems	4x Seetrax Ranger
Schematic	Ranger schematic entry
Mechanical layout	Solidworks / BricsCAD
Throughput	50+ designs / month
Board types	Library of all system types
Expertise	>5000 BIB designs
Technology	Impedance matched, stripline, fine pitch and high power layouts

Materials

Laminates <125°C	High Tg FR4
Laminates <250°C	Polyimide
Laminates <300°C	High grade polyimide
Solders	Sn/Ag lead free
Plating	Full / selective Ni and Au
Coatings	Silicone conformal coat
Board supports	Aluminium and stainless

Design



Assembly



Test



BIB Specification

Panel size	32" x 32"
No of layers	14layers
Pitch spacing	0.3mm (WLCSP / CSP)
Trace widths	3mil spacing
Board plating	Ni and Au finishes
Device pincounts	>2000 pins
Maximum temperature	300°C
Maximum Voltage	10KV
Technology	Microvia, blind, buried, capped
Socket types	Enplas, Sensata, Plastronics, Yamaichi, LIC, Aries, etc

Manufacturing

Component placement	Automatic glue dot
Component loading	Quad pick and place
Assembly	SMT or thru hole
Throughput	15000 placements per hour
Capacity	250 boards / week
Baking	Blue M bake chamber
Soldering	Invicta Dual solder wave
Cleaning	Kerry Ultrasonic cleaning
Conformal coating	Silicone coating process
Board test	Bibtest55 XL BIB test
Product Conformance	ISO9001:2008 certified



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